	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Commen
1	BRS	L1		49	xu near chongying.in.	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 16:07	
2	BRS	L2		195		US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 16:07	
3	BRS	L3		8	korzenski near michael.in.	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 16:08	·

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Commen
4	BRS	L4		580	(supercritical pear		2004/11/ 16 17:17	
5	BRS	L5		54	·	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 16:20	
6	BRS	L6		4	(carbon near dioxide) near5 (fluid) near15 (precursor) near20 (substrate or wafer)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 16:22	

	Туре	L	#	Hits	Search Text	DBs	Time Stamp	Commen
7	BRS	L7		68	(deposit\$3) near5 (fluid) near15	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 16:31	
8	BRS	L8		11	(deposit\$3) near5 (supercritical near fluid) near15 (precursor) near20 (substrate or wafer)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 16:32	
9	BRS	L9		71	(deposit\$3) near5 (supercritical near fluid) near20 (substrate or wafer)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 16:39	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Commen ts
10	BRS	L10	68	(fluid) near15	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 16:39	
11	BRS	L11	395	(fluid) near15 (precursor) near20 (substrate or wafer)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 17:13	•
12	BRS	L12	75	(supercritical) near15 (precursor) near20 (substrate or wafer)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 17:13	

	Type	L	#	Hits	Search Text	DBs	Time Stamp	Commen
13	BRS	L1	3	0		US- PGPU B; USPA T; EPO; DERW ENT; IBM_ TDB	2004/11/ 16 17:17	
14	BRS	L1	4	372	(supercritical or fluid) near10 (precursor) near20 (substrate or wafer)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 17:27	
15	BRS	L1	5	75	14 and (carbon near dioxide)	US- PGPU B; USPA T; EPO; JPO; DERW ENT; IBM_ TDB	2004/11/ 16 17:28	

	ט	1	PT	P	Document ID	Issue Date	Page s	Title
1	Х				US 2004011286 5 A1	20040617	ا <sup>ل</sup>	Method to build a microfilter
2	Х				US 2004002345 3 A1	20040205		Supercritical fluid- assisted deposition of materials on semiconductor substrates
3	Х				US 2003012478 5 A1	20030703	10	Supercritical fluid- assisted deposition of materials on semiconductor substrates
4					US 6805801 B1	20041019		Method and apparatus to remove additives and contaminants from a supercritical processing solution

	บ	1	PΤ	P	Document ID	Issue Date	Page s	Title
5					US 5509959 A		16	Precursor coating compositions suitable for spraying with supercritical fluids as diluents

	υ	1	PT	P	Document ID	Issue Date	Page s	Title
6					US 5466490 A	19951114	26	Precursor coating compositions containing water and an organic coupling solvent suitable for spraying with supercritical fluids as diluents
7					US 5374305 A	19941220	26	Precursor coating compositions containing water and an organic coupling solvent suitable for spraying with supercritical fluids as diluents
8					US 5066522 A	19911119	39	Supercritical fluids as diluents in liquid spray applications of adhesives
9					US 2004002345 3 A	20040205	15	Deposition composition for depositing material (e.g. low dielectric constant organosilicate film and barrier layer) on substrate, comprises supercritical fluid and precursor of material to be deposited on substrate

	บ	1	PT	P	Document ID	Issue Date	Page s	Title
10	Х				US 2003012478 5 A	20030703		Deposition composition for depositing material, e.g. semiconductor material, on substrate comprises supercritical fluid
11	X				EP 453107 B	19950301	11	Chemical deposition using supercritical fluid solns for high quality thin films of mixed metal oxide high temp. superconducting cpds.